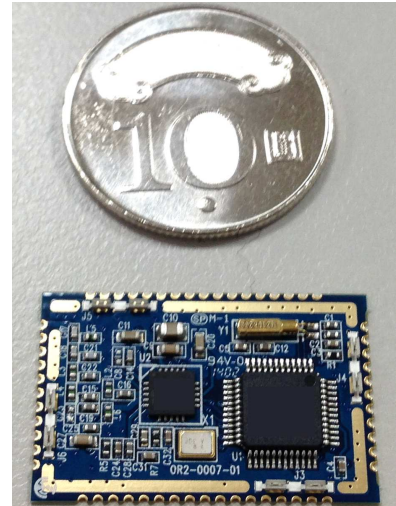


Wireless ED Module_9 series

Feature Highlights

- Low voltage operation: 2.0V – 3.6V
- Compact size: 4cm x 2cm, ideal for embedded system
- Low-power consumption
- Lengthened battery life when used in M2C Platanus™ platform
- ARM Cortex-M0 up to 32MHz clock rate, with embedded 128 KB flash memory and 16 KB SRAM
- Frequency range: 903~927MHz
- Data bandwidth: up to 500kbps
- High receiver sensitivity: -96dBm at 500kbps
- Integrated power amplified up to 3.96dBm
- Support I²C, UART, SPI, Fast IRQ and GPIOs for control interface
- Up to 4-channel, 12-bit ADC available for sensor interface
- Pre-matched RF front-end, reducing design hassles
- Ready-to-go Access point with TCP/IP gateway and Router are available (sold separately)
- Supports 128-node “star” and 16000-node “tree” network infrastructure.



Applications

- Comply with FCC Part 15C
- Low-cost solution for ultra-low power wireless link
- Remote control systems
- Wireless sub-metering (plug)
- Home automation
- Wireless sensor network
- Telemedicine service
- Wireless lighting control
- Smart rack system

Descriptions

Overview

MD903A1 is an easy-to-integrate low-power module for wireless-link application. With state-of-the-art Platanus™ protocol and networking kit, large network (up to 16000 nodes) can be easily formed. Equipped with ISM-band RF operated at 903~927MHz bands and popular ARM Cortex M0 32-bit MCU along with embedded flash memory and SRAM, MD903A1 is an ideal embedded solution for system integrator to develop wireless applications with no worry about design hassles.

Easy to Integrate and Use

Designed as the LAN module, MD903A1 has only the board area of 4cm x 2cm, compact enough for most embedded system design. An on-board antenna has been built (with option to be connected to the external antenna) and the RF matched network is calibrated to optimize the RF performance when the module is shipped, saving the design hassles for application designers.

There are total 27 stamp pads on MD903A1 with multiple digital/analog interfaces: 1x I2C, 1xSPI, 2xUART, 29xGPIOs, 1x Fast Interrupt, 3xPWMs and also up to 4-channel 12bit-ADC. This brings the design flexibility to end applications that MD903A1 is easy to interface with peripheral controls and sensors. Through the robust wireless link, controlled/collected information can be easily exchanged with the upper application layers.

Ready-to-go Sub-GHz Radio Link with Excellent Reliability

The wireless link utilizes the sub-GHz radio band, requiring no special licenses (free-ISM) and certification. MD903A1 comply with the FCC part 15C regulations. Compared to the crowded 2.4GHz band, sub-GHz radio link allows better distance and penetration especially in the hostile indoor environment. In particular, with WiFi and Bluetooth packed the 2.4GHz band these days, MD903A1 is immune from the 2.4GHz interference and delivers the reliable wireless link. With the data rate of 500kbps in 2FSK, the bandwidth use efficiency is 16x better than 2.4GHz Zigbee (2MHz). MD903A1 can deliver the link budget up to 107dB (TX maximum power: 11dBm, RX Sensitivity level: -96dBm) without external adding components. The Line-of-Sight (LOS) link distance is over 300 meters.

Robust Two-way Networking

MD903A1 has a built-in protocol Platanus™ to support “two-way” networking, saving the SI’s design headache of linking large amounts of wireless nodes. When used with MA901A1 (Access Point), MD903A1 can support two types of network hierarchies: STAR and TREE (as shown below). When MD903A1 is configured in STAR networking, up to 250 nodes can be supported. When MD903A1 is configured in TREE network, up to 16000 nodes can be supported. Asymmetrical downlink and uplink are supported to balance between network reliability and response time, and the programmable network parameters can be used to optimize for each use scenario. Figure 1 is START network, figure 2 is TREE network.

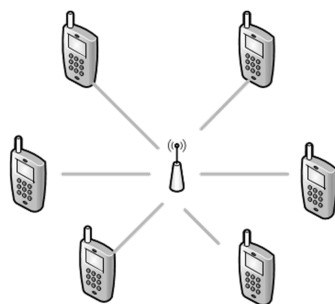


Figure 1. STAR configuration

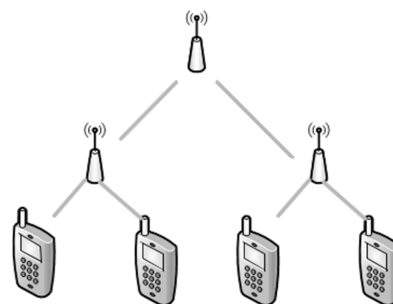


Figure2. TREE configuration

TCP/IP Connectivity

Each MD903A1 is assigned a 4-byte MAC address, and assigned a unique network ID when joining a network. M2C’s MA901A1 (Access Point) has already been shipped with the TCP/IP gateway and the managing software library. Thus the upper-layer application layer can access each MD903A1 in the network to exchange data “two-way” via the Ethernet or WiFi. This makes the cloud-based application developer easy to hook up with the privately-own network when building with MD903A1.

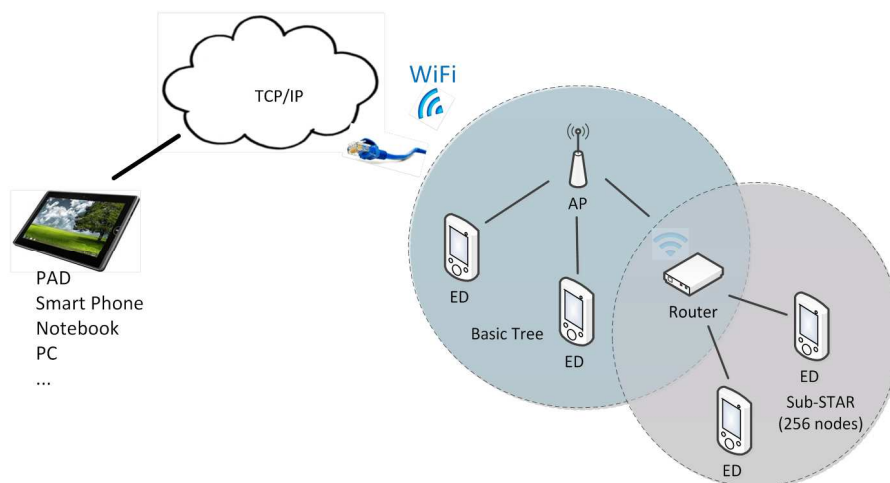


Figure 3. Network Structure

Ideal Platform for Low-power Application Development

MD903A1 is powered by ARM Cortex-M0 with clock up to 32MHz with embedded 128K-Byte flash and 16K-Byte SRAM, to support built-in Platanus™ networking library from M2C and for peripherals, such as GPIO controls or serial data interfaces. The function calls for Platanus™ can be linked to the main program during elaboration to enable the wireless accessibility. The command library is available for development. For details, please refer to the associated documentation.

Used with patented Platanus™ protocol used with M2C MA901A1 (Access Point) and/or MR1001 (Router), MD903A1 can achieve ultra-low power consumption for battery-friendly applications. The network acts in the cellular-like behavior, with sleep time configurable from 5 seconds up to 90 seconds. The reference average power consumption is as below. This only reflects the wireless link, excluding the peripherals.

Sleep Time	Reference Average Current Consumption
5 seconds	36.8 μ A
30 seconds	15.2 μ A
90 seconds	9.5 μ A

Pin Diagram & Components Placement

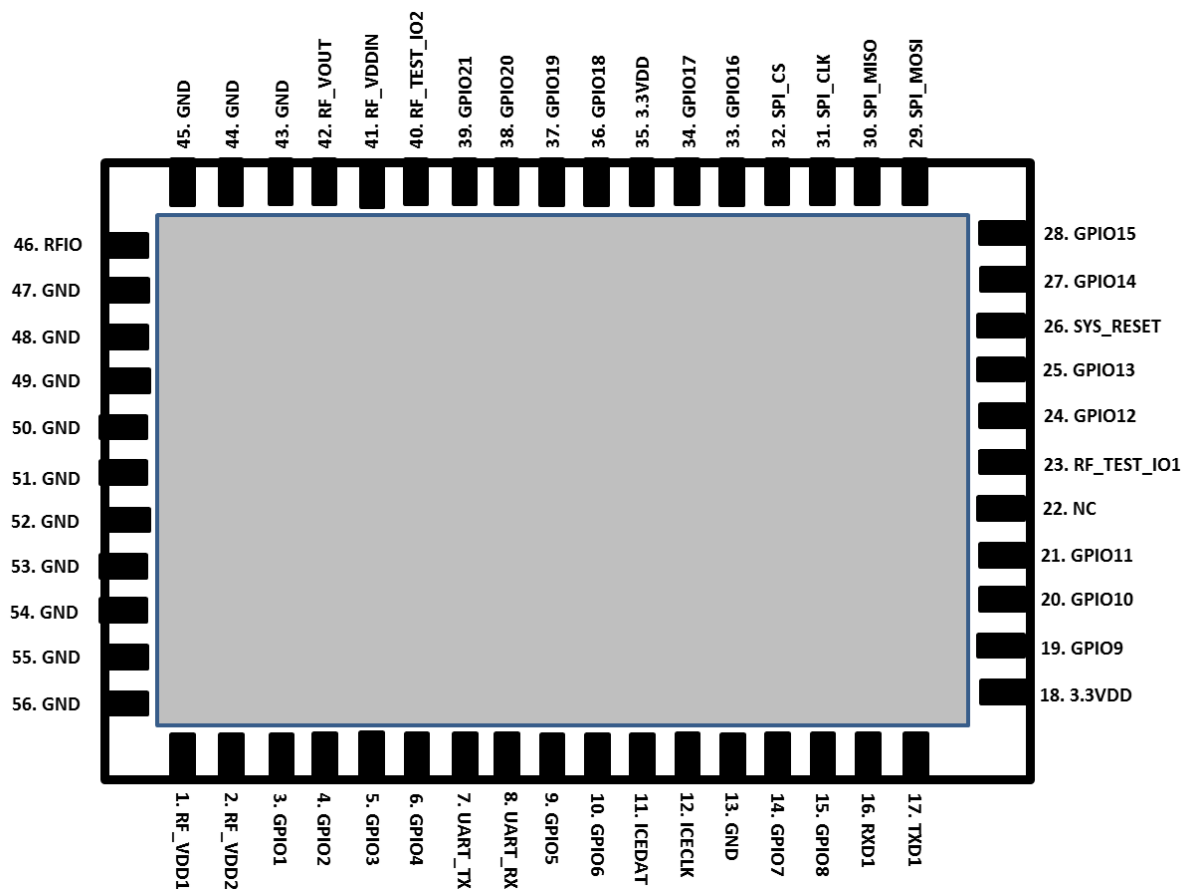


Figure4. Pin diagram

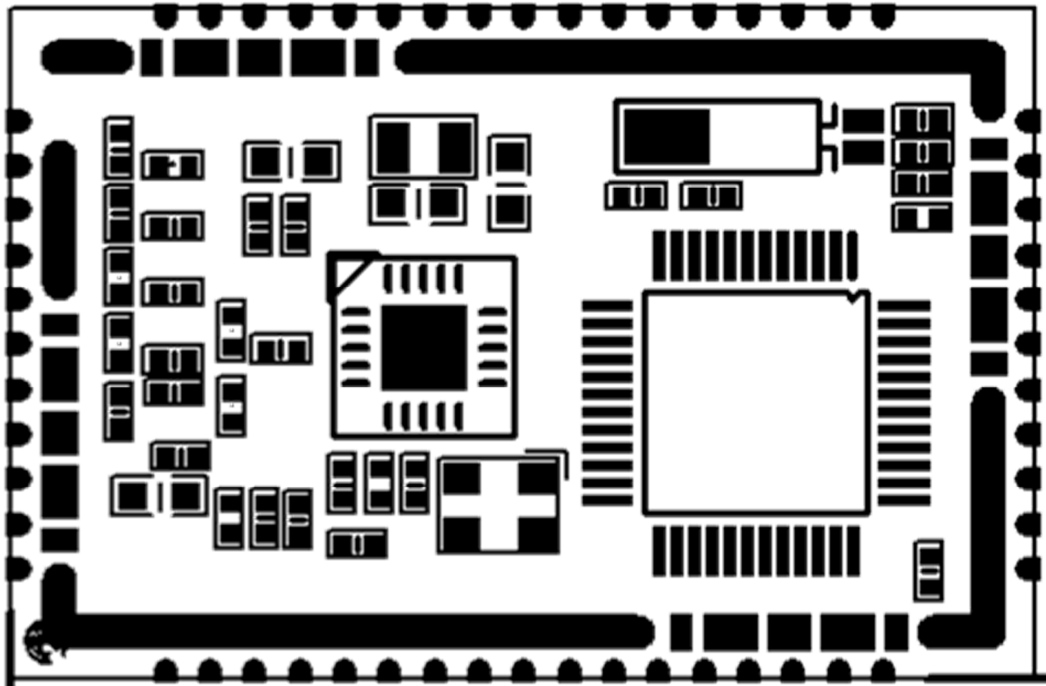


Figure5. Components placement

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1 Electrical Characteristics

Table 1. Absolute Maximum Rating

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage	V_{dd}	VCC to GND	-0.3		3.6	Volt
Voltage on I/O Pin	V_{IO}		-0.3		$V_{CC} + 0.3$	Volt
Temperature Range for Storage	T_{sto}		-10		+85	°C
Operation Temperature	T_{opt}		0		+45	°C

Table 2. DC Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Power Supply	V_{dd}	see note 1	2.0		3.6	V
Low-power Current Consumption	I_{normal}	(see below)		N/A		
	$I_{standby}$	Standby mode		4		mA
	I_{deep_sleep}	Deep-sleep mode			5	μA
RX Mode Current Consumption	$I_{RX,MB}$	Data rate = 500kbps 2FSK			26	mA
TX Mode Current Consumption	$I_{TX1, 11dBm}$	Output power = 11.32dBm			50	mA

Note 1: all performance parameters are guaranteed at $V_{dd} = 3.3V$

Table 3. AC Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
RF						
Frequency Range	F_{915M}		903		927	MHz
RX Sensitivity	P_{Rx_500K}	BER < 0.1% 2FSK, BT=0.5 500Kbps		-96		dBm
Saturation Power Level	P_{sat}			10		dBm
RSSI Range	RES_{RSSI}		-82		-58	dBm
Output TX Power	P_{out}		-3		11	dBm
RF Data Rate	DT			500		Kbps
Link Distance	R_{link}	Line-of-Sight 20-byte packet length PER<1% $P_{out} = 10dBm$		250		Meters
Link Distance	R_{link}	Line-of-Sight 20-byte packet length PER<1% $P_{out} = 0dBm$		110		Meters
ADC						
Max. Input Signal	V_{in}			1.5		Volt
Source Impedance	Z_{in}				10K	Ω
Resolution	ENOB			12		bit
Conversion time	T_{conv}			1.25		μSec
Differential Non-linearity	DNL			+/- 4	+/- 8	LSB
Integral Non-linearity	INL			+/- 4	+/- 8	LSB

Table 4. Digital IO Specification

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Rise Time	T_r	10% to 90% of VCC CL=10pF, DR<1:0>=11		10		ns
Fall Time	T_f	10% to 90% of VCC CL=10pF, DR<1:0>=11		10		ns
Logic "H" Input Level	V_{IH}			VDD-0.6		V
Logic "L" Input Level	V_{IL}			0.6		V
Input Capacitance	C_{pin}			1		pF
Input Impedance	$Z_{pin,hiZ}$	DC, Configured as hi-Z	10M			Ω
	$Z_{pin,pl}$	DC, Configured as pull-low		100K		Ω
	$Z_{pin,ph}$	DC, Configured as pull-high		100K		Ω
Maximal Output Current	I_{drive}	programmable	1	4	8	mA
Logic "H" Output Level	V_{OH}			VDD-0.5		V
Logic "L" Output Level	V_{OL}			0.5		V

Digital I/O Specification Annotation

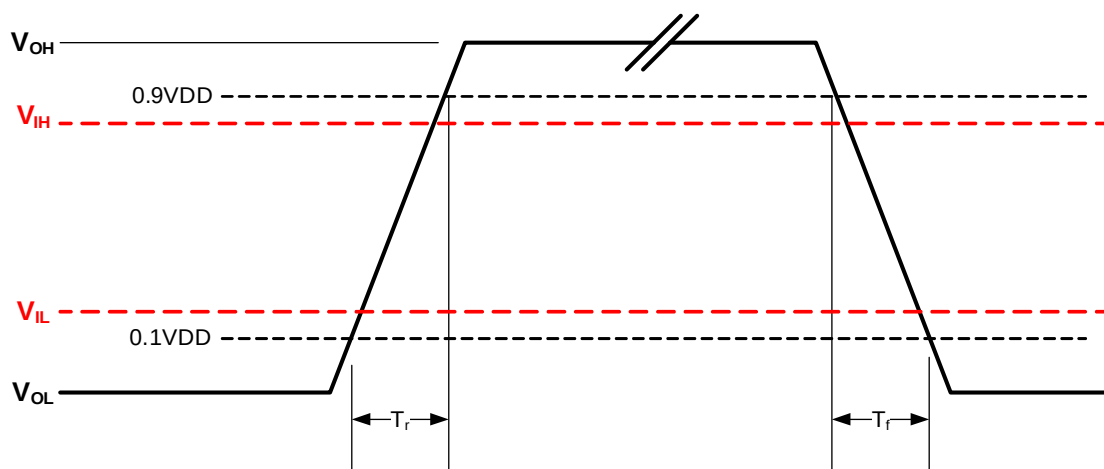


Figure6. I/O level diagram

2 Pin Out

All VDDs are rated from 2.0V to 3.6V.

Pin #	Pin Name	Description	Type[1]	I/O/PWR
1	RF_VDD1	RF Power Input, connected with RF_VOUT	P	PWR
2	RF_VDD2	RF Power Input, connected with RF_VOUT	P	PWR
3	GPIO1	GPIO/PWM1	D	IO
4	GPIO2	GPIO/PWM2	D	IO
5	GPIO3	GPIO	D	IO
6	GPIO4	GPIO	D	IO
7	UART_TXD	UART0_TXD output (debugger)	D	O
8	UART_RXD	UART0_RXD input (debugger)	D	I
9	GPIO5	GPIO/I2C_CLKOUT/PWM3	D	O
10	GPIO6	GPIO/I2C_DATA/PWM4	D	IO
11	ICEDAT	ICE DATA IN (debugger)	D	IO
12	ICECLK	ICE CLK (debugger)	D	I
13	GND	Board ground	G	0
14	GPIO7	GPIO/ADC0	D/A	IO
15	GPIO8	GPIO/ADC1	D/A	IO
16	RXD1	UART1_RXD	D/A	IO
17	TXD1	UART1_TXD	D/A	IO
18	3.3VDD	Module Power Input. 2.0V~3.6V (10mA requirement)	P	PWR
19	GPIO9	GPIO/ADC3	D/A	IO
20	GPIO10	GPIO/ADC4	D/A	IO
21	GPIO11	GPIO	D	IO
22	NC	RESERVED for USED		
23	RF_TEST_IO1	RF_TEST_IO1	D	IO
24	GPIO12	GPIO	D	IO
25	GPIO13	GPIO	D	IO
26	SYS_RESET	External reset input[2]	SYS	SYS
27	GPIO14	GPIO	D	IO
28	GPIO15	GPIO	D	IO
29	SPI_MOSI	SPI Data Out, MOSI	D	O
30	SPI_MISO	SPI Data In, MISO	D	I
31	SPI_CLK	SPI Clock Output	D	O
32	SPI_CS	SPI Chip Select	D	O

33	GPIO16	GPIO	D	IO
34	GPIO17	GPIO	D	IO
35	3.3VDD	Module Power Input. 2.0V~3.6V (10mA requirement)	P	PWR
36	GPIO18	GPIO	D	IO
37	GPIO19	GPIO	D	IO
38	GPIO20	GPIO	D	IO
39	GPIO21	GPIO	D	IO
40	RF_TEST_IO2	RF_TEST_IO2	D	IO
41	RF_VDDIN	Module RF Power Input. 2.0V~3.6V (70mA requirement)	P	PWR
42	RF_VOUT	LDO Output for RF_VDD1 and RF_VDD2	P	PWR
43~45	GND	Board ground	G	0
46	RFIO	RF Signal 50 ohm	IO	RF
47~56	GND	Board ground	G	0

[1] D=digital, A=analog, P=power, G=ground

[2] Set this pin low reset chip to initial state, with internal pull-up

[3] External interrupt input

3 Memory

MD903A1 is equipped with embedded 128KB flash memory and 16KB SRAM. The specification is listed as below.

Currently MD903A1 does not support the external memory due to performance compromises,

4 Serial Interfaces

MD903A1 support the common serial data interfaces, including GPIO, SPI, I²C, and UART. Their timing and specifications are addressed at the following sections.

4.1 General-purpose I/O (GPIO)

The functions of GPIOs are summarized as below:

- Push-Pull output
- Open-Drain output
- Input only with high impedance (100K ~ 300Kohms)
- All inputs with Schmitt trigger
- I/O pin configured as interrupt source with edge/level setting
- Supports input 5V tolerance

4.2 SPI

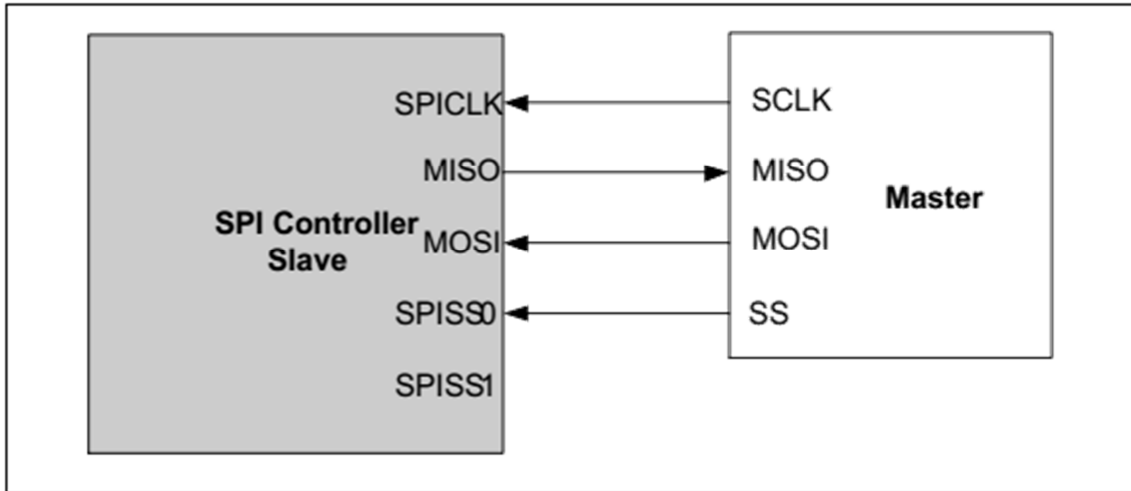


Figure7. SPI Slave Mode Application Diagram

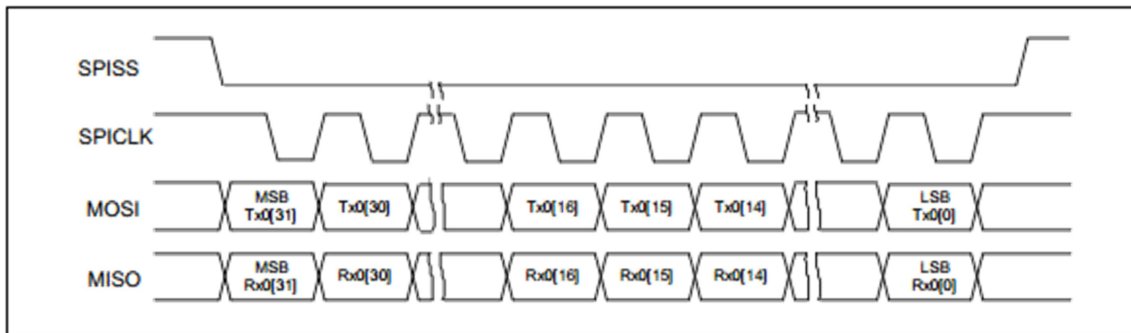


Figure8. SPI 32-bit In One Transaction

The features of SPI interfaces are summarized as below:

- One SPI master controller
- Support clock rate up to 10MHz
- Configurable bit length of a transaction from 8 to 32-bit
- Supports byte re-ordering function
- LSB first or MSB first
- Selectable polarity of serial clock idle state

4.3 I²C

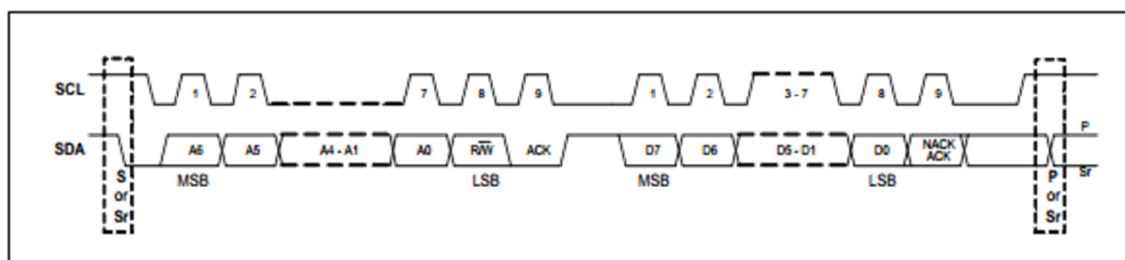


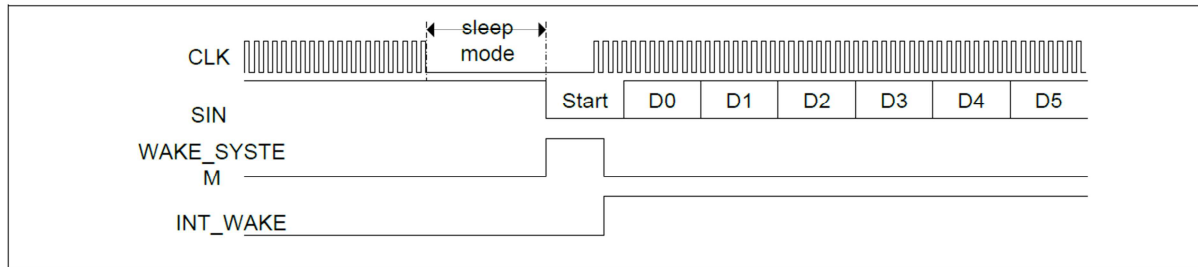
Figure9. I²C Protocol (7-bit addressing mode)

The features of I²C interfaces are summarized as below:

- I²C master supports up to 1MHz transfer rate
- Bidirectional data transfer between master and slave devices
- A master-transmitter addresses a slave receiver with a 7-bit address.

4.4 UART

Data Wake-Up



UART DATA Wake-Up



Figure10. UART Data Format

The features of UART interfaces are summarized as below:

- Two sets of UART controllers
- The UART0 and UART1 are built-in with a 16-byte TX_FIFO and a 16-byte RX_FIFO to reduce the number of interrupts presented to the CPU
- Baud rate is up to 460800 bps
- Support IrDA (3/16 bit modulation) function mode (optional)

4.5 PWM

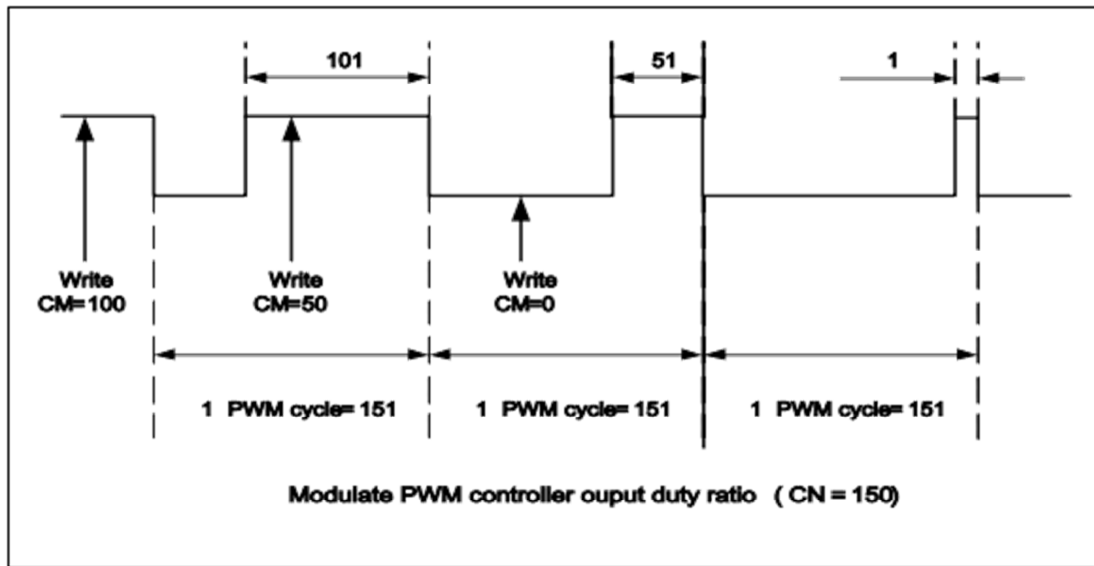


Figure11. PWM-Timer Operation Timing

The features of PWM interfaces:

- One 16-bit PWM controller with three output/inputs, for period and duty-cycle adjustment flexibility
- Each PWM output can be configured as one-shot mode to produce only one PWM cycle signal or continuous mode to output PWM waveform continuously
- Digital capture functions can latch the rising or falling transition at these inputs when configured.

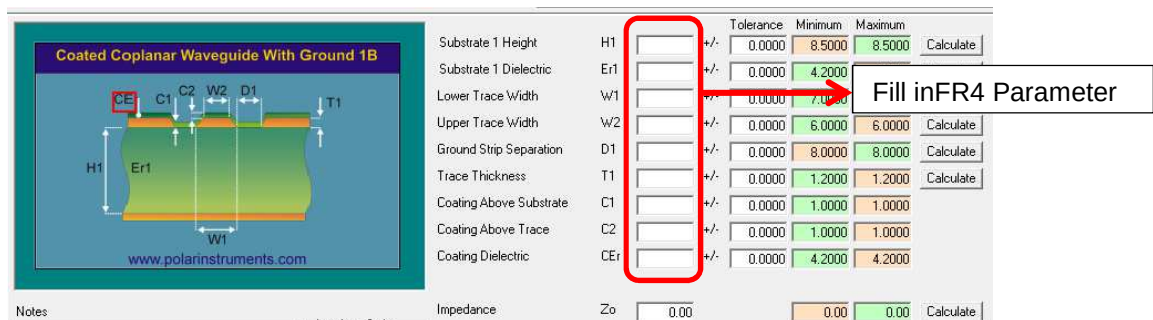
5 How to Use MD903A1 to Design & Compliance with FCC requirements

The MD903A1 is a proprietary product design and manufactured by M2C (M²Communication Inc.) for integrated into wireless products manufactured by M2C for sub 1GHz ISM communication application. And the chapter will complete explain how to design MD903A1 on product.

5.1 50ohm RF Trace Calculation

The MD903A1 module has 50ohm impedance RF output pin (RFIO) to connect external antenna on carried board (or called Mother Board). RF trace on carried board is between RF output pin of MD903A1 and antenna on carried board and the trace must is 50ohm to obtain best RF performance. Also, 50ohm trace is recommended for PCB layout.

Engineer (or Developer) can use “PCB Transmission Line calculation tool” (example: Polar) to obtain value about RF layout information on PCB. Engineer just fill in value that FR4relative parameter in “PCB Transmission Line calculation tool”, include PCB stack, substrate height, PCB dielectric, trace thickness....etc. 50ohm transmission line dimension can be got from the tool. Below figure show the PCB Transmission Line calculation tool.



Parameter	Symbol	Units	Tolerance	Minimum	Maximum	Calculate
Substrate 1 Height	H1		+/-	0.0000	8.5000	8.5000
Substrate 1 Dielectric	Er1		+/-	0.0000	4.2000	4.2000
Lower Trace Width	W1		+/-	0.0000	7.0000	7.0000
Upper Trace Width	W2		+/-	0.0000	6.0000	6.0000
Ground Strip Separation	D1		+/-	0.0000	8.0000	8.0000
Trace Thickness	T1		+/-	0.0000	1.2000	1.2000
Coating Above Substrate	C1		+/-	0.0000	1.0000	1.0000
Coating Above Trace	C2		+/-	0.0000	1.0000	1.0000
Coating Dielectric	CEr		+/-	0.0000	4.2000	4.2000

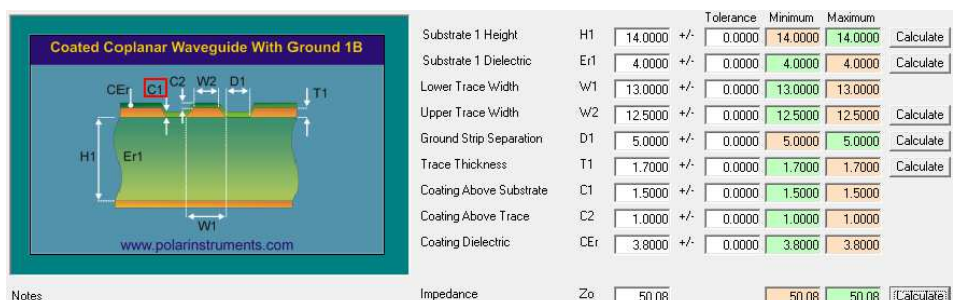
Figure12. Trace design for the PCB layout

Example: Use 2-layer FR4 PCB to design 50ohm trace

The figure 13 is 2-layers FR4 PCB parameter (PCB stack). The RF trace width and spacing that is between RF trace and ground plane and others value that is 50ohm design requires is show in figure 14.

PCB Stack Up					
Layer	Type		Thickness (mil)		DK
		Top side solder mask	1.00	mils	3.8
L1	TOP	Differential & Signal	copper+plating	1.70	mils
		core	14.00	mils	4
L4	Bottom	Differential & Signal	copper+plating	1.70	mils
		Bottom side solder mask	1.00	mils	3.8
TOTAL			19.40	mils	
			0.49	mm	

Figure13. 2-layer FR4 PCB stack



Parameter	Symbol	Units	Tolerance	Minimum	Maximum	Calculate
Substrate 1 Height	H1		+/-	0.0000	14.0000	14.0000
Substrate 1 Dielectric	Er1		+/-	0.0000	4.0000	4.0000
Lower Trace Width	W1		+/-	0.0000	13.0000	13.0000
Upper Trace Width	W2		+/-	0.0000	12.5000	12.5000
Ground Strip Separation	D1		+/-	0.0000	5.0000	5.0000
Trace Thickness	T1		+/-	0.0000	1.7000	1.7000
Coating Above Substrate	C1		+/-	0.0000	1.5000	1.5000
Coating Above Trace	C2		+/-	0.0000	1.0000	1.0000
Coating Dielectric	CEr		+/-	0.0000	3.8000	3.8000

Impedance Zo: 50.08

Figure14. 50ohm parameter of 2-layers FR4

5.2 PCB Design

MD903A1 provides 3 antennas (frequency: 902MHz~928MHz) for engineer chooses, one is PIFA type antenna; the other two are dipole antenna. About antenna manufacturer and model number can refer chapter 7.

When using dipole antenna on carried board, just need to make sure the impedance of RF trace is 50ohm, as below figure 15.



Figure15-1.Reversed SMA connector to connect dipole antenna

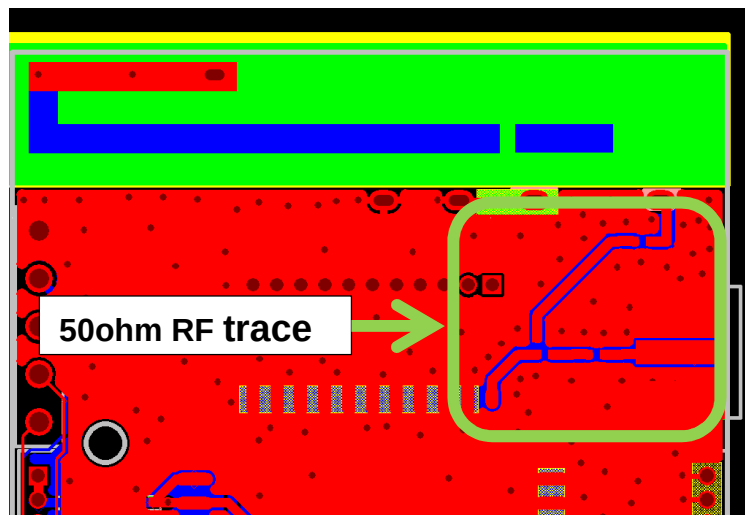


Figure15-2.Reversed SMA connector to connect dipole antenna

When using PIFA antenna in design PCB, need to make sure the impedance of RF trace is 50ohm. Structure of PIFA antenna can separate two parts. One is metal part that solder on PCB; the other is antenna trace on PCB. The different antenna trace length has different center frequency. Engineer can use network analyzer to fine-tune antenna trace length, so that antenna can work on required frequency (902MHz~928MHz). The trace dimension in figure18 is recommended to PCB layout.

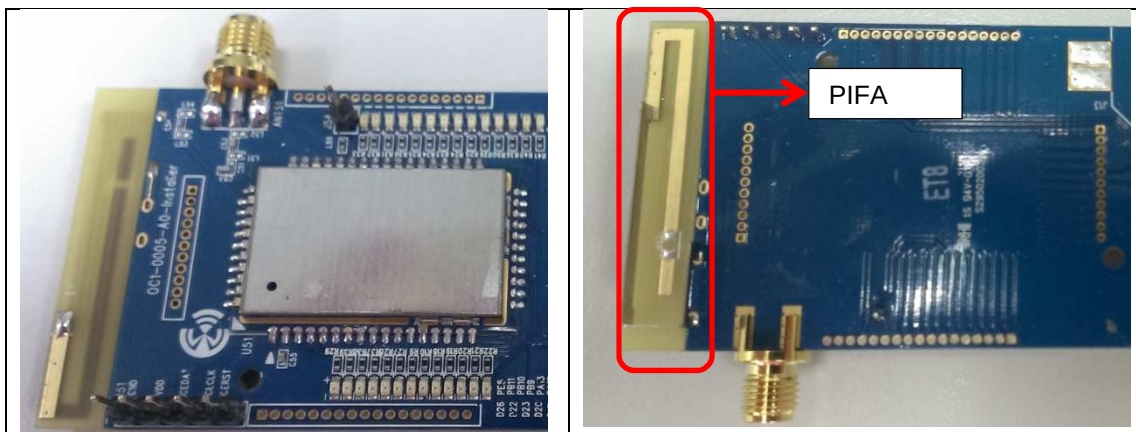


Figure16. PIFA antenna

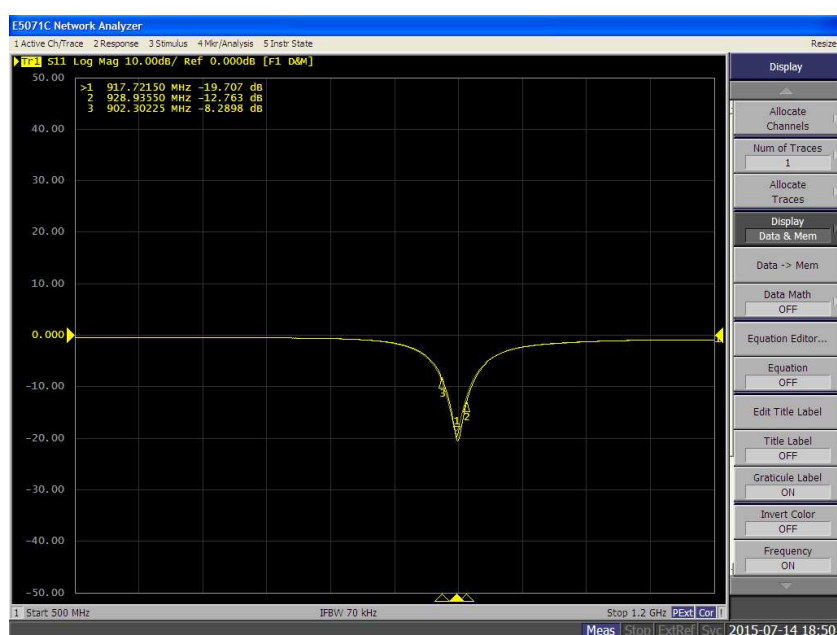


Figure17. Network analyzer to check frequency & return loss

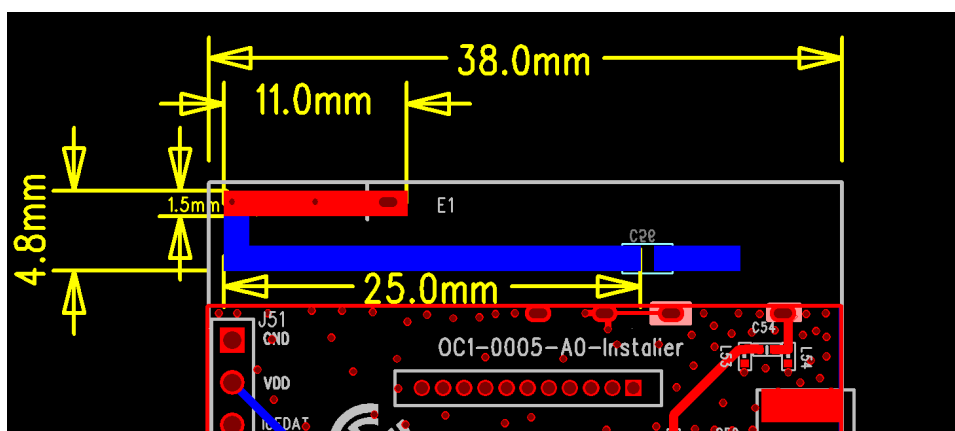


Figure18. PIFA antenna trace dimension

5.3 PCB Layout Recommend

- RF connector: Reversed SMA connector.
- RF trace length is less 80mm.

5.4 PCB Layout Guide

Some general rules of thumb for designing RF-related layouts for good RF performance are:

- Use as much continuous ground plane metallization as possible.
- Avoid the separation of the ground plane metallization at RF area.
- Use as many grounding vias (especially near to the GND pins) as possible to minimize series parasitic inductance between the ground pour and the GND pins.
- Use a series of GND vias (a so called “via curtain”) along the PCB edges and internal GND metal pouring edges. The maximum distance between the vias should be less than $\lambda/10$ of the 10th harmonic. This is required to reduce the PCB radiation at higher harmonics caused by the fringing field of these edges.
- Avoid using long and/or thin transmission lines to connect the components. Otherwise, due to its distributed parasitic inductance some detuning effects can occur.
- Avoid using loops and long wires to obviate its resonances.
- Always ensure good VDD filtering by using some bypass capacitors (especially at the range of the operating frequency).

6 Antenna Characteristics

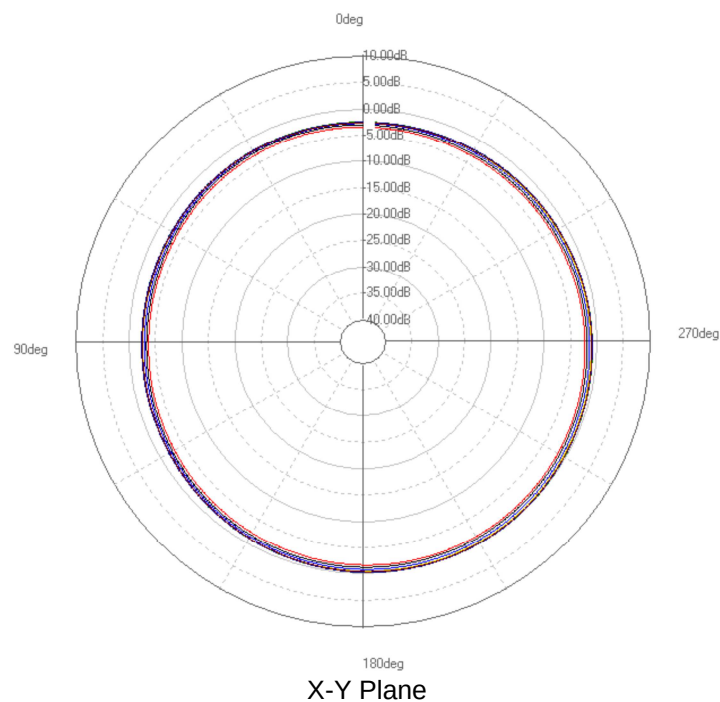
The MD903A1 RF module have 50ohm RF output pin (RFIO) to connect external 902MHz~928MHz antenna via carried board. The choice of antenna is limited to the antenna types the module has been tested with. Refer to Section 8 “Regulation Approval” for a list of tested and approved antenna types that may be used with the MD903A1 module.

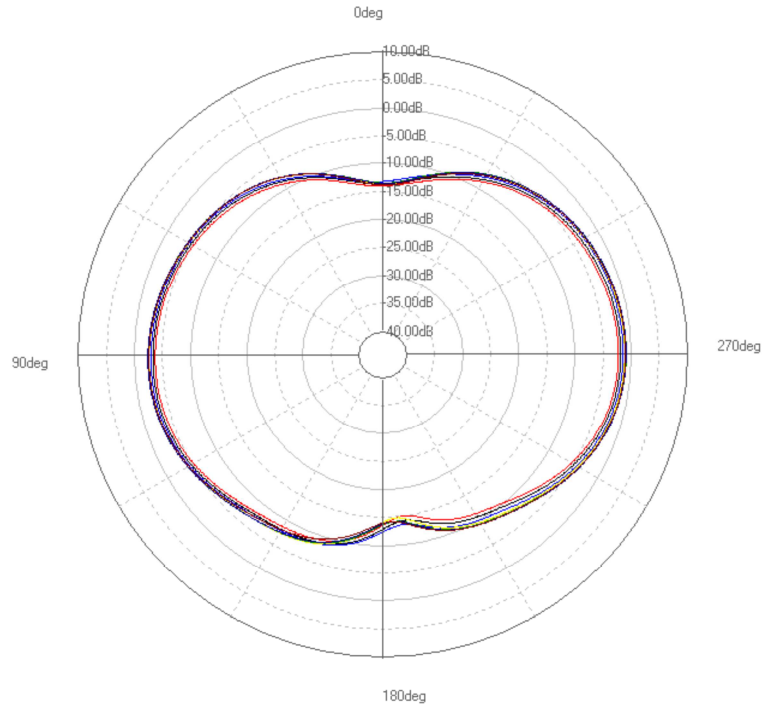
A list of antenna approved for use with the module is provided as below table.

Antenna Type	Peak Gain	Model No.	Manufacturer
PIFA	0.3dBi	AN14-000079	RESILIENT
Dipole	1.42dBi	CWX-614XSAXX-999	JOYMAX
Dipole	2dBi	GWX-282XSABX-991	JOYMAX

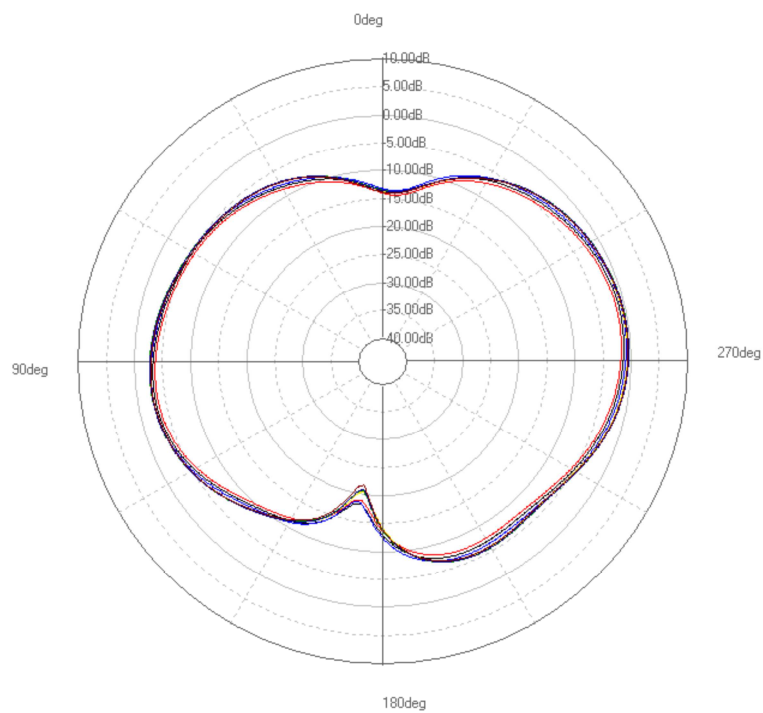
Below antenna's pattern are measured and provide by vender.

- PIFA / AN14-000079



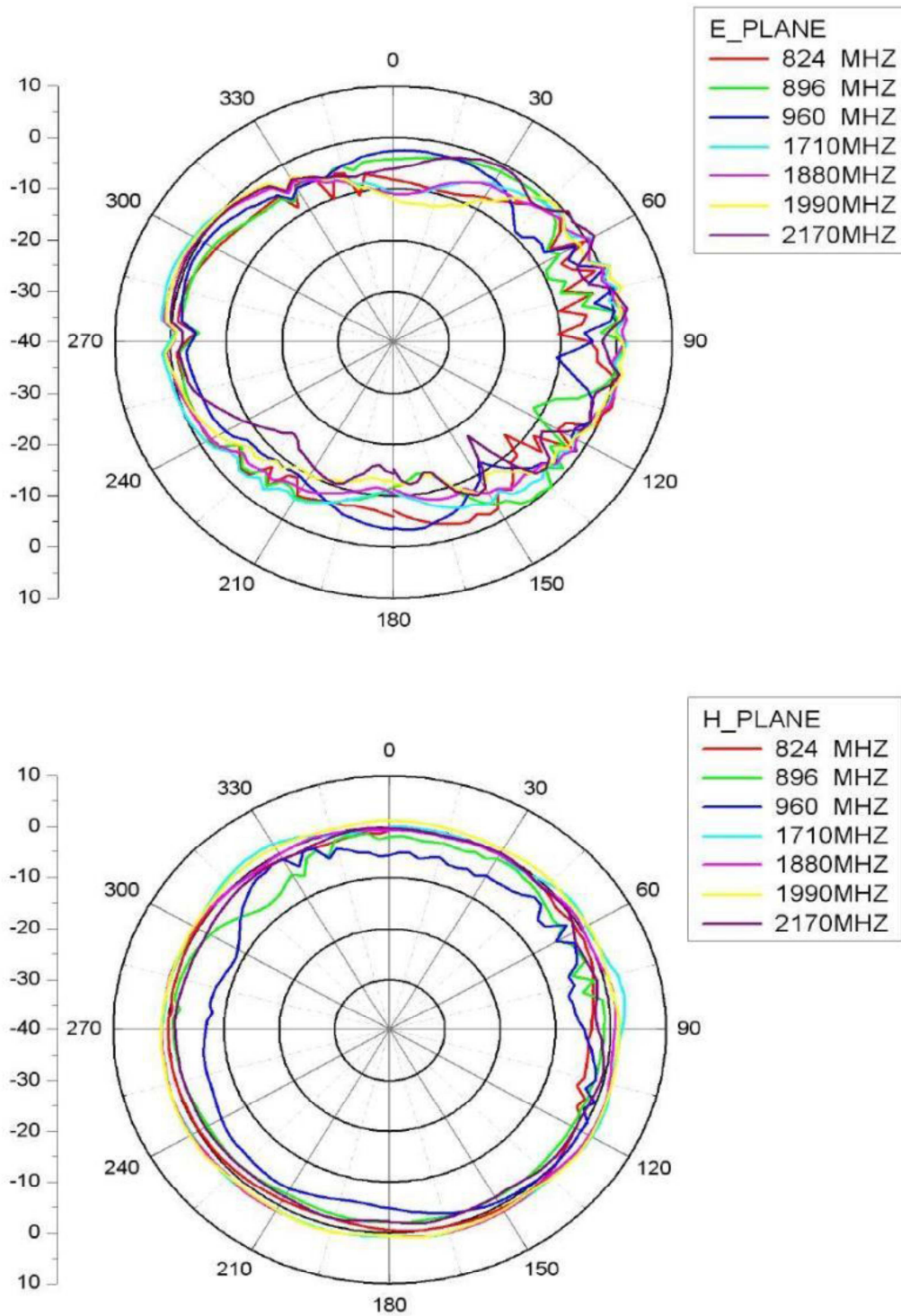


Y-Z Plane



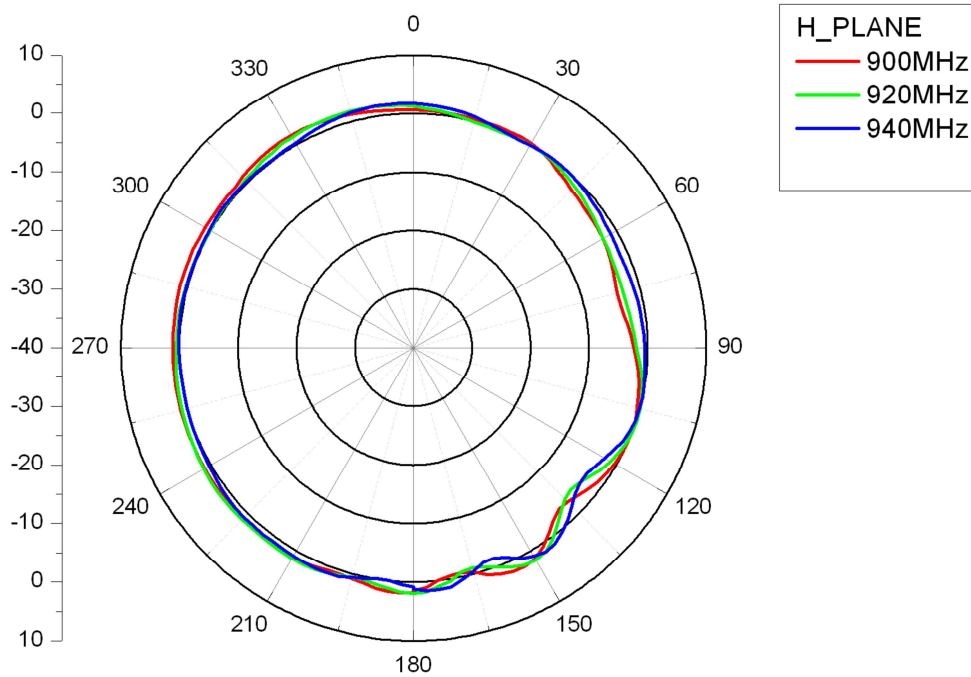
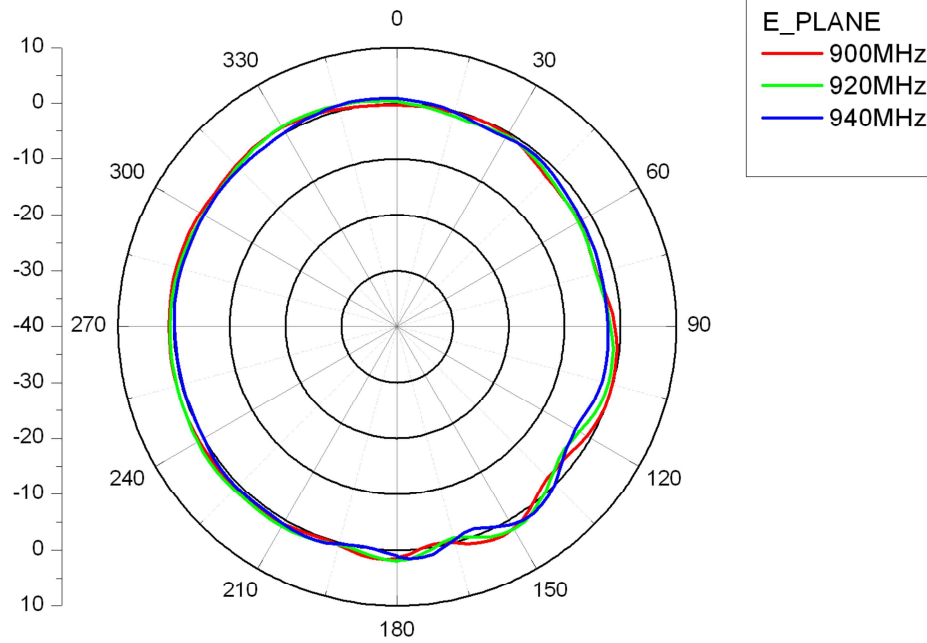
X-Z Plane

- Dipole / CWX-614XSAXX-999





- Dipole / GWX-282XSABX-991



7 Regulation Approval

The MD903A1 module has received regulatory approvals for modular device in the United States. Modular approval allows the end user to place the MD903A1 module inside a finish product and not require regulatory testing for an intentional radiator (RF transmitter), provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the grantee, which indicate installation and/or operating conditions necessary for compliance.

The MD903A1 has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" 15.247 and modular approval in accordance with Part 15.212 modular Transmitter approval. The MD903A1 module can be integrated into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation.

The MD903A1 module has been labeled with its own FCC ID number and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording as follows:

Contain Transmitter module FCC ID : **2AFXU-MD903A1**

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) This device may not cause harmful interference, and (2) this device must accept any interference received ,including interference that may cause undesired operation.

8 Recommended PCB Footprint

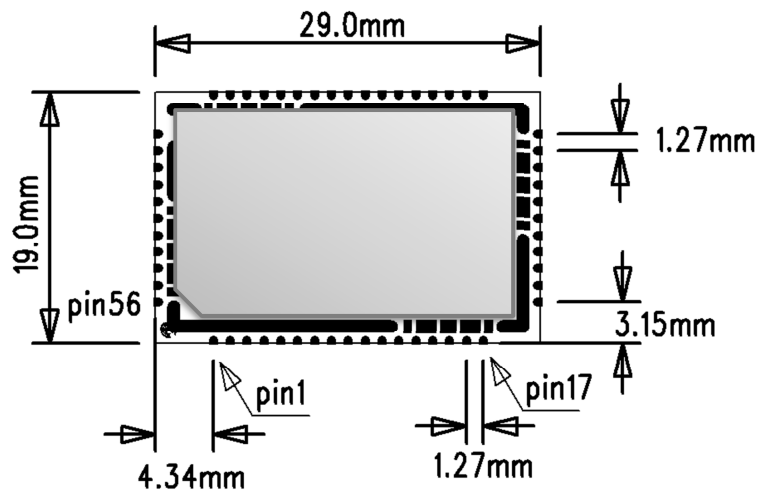


Figure19. Top View Outline Dimension

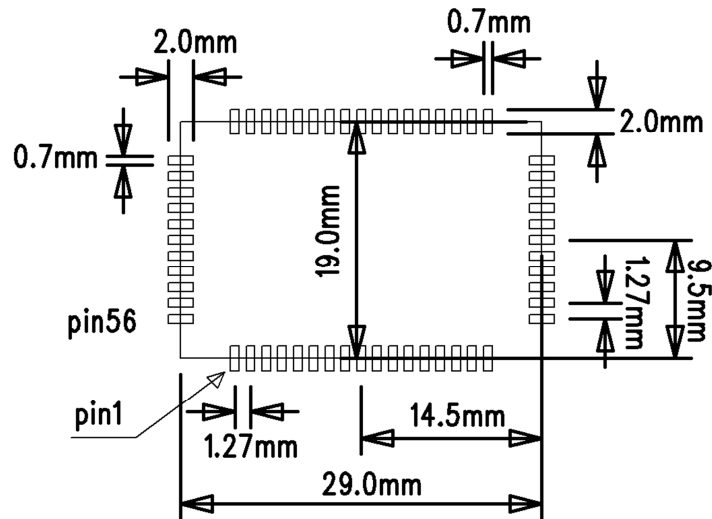


Figure20. Recommend PCB Footprint

9 Order Information

Ordering Part Number	Frequency Band	Product Description
MD903A1	903~927MHz	MD903A1 with 50-ohm output for external antenna

10 Contact Information

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FCC Statement:

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located with any other transmitters except in accordance with FCC multi-transmitter product procedures.

Referring to the multi-transmitter policy, multiple-transmitter(s) and module(s) can be operated simultaneously without C2P.

IMPORTANT NOTE:

FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator & your body.

IMPORTANT NOTE:

This module is intended for OEM integrator. The OEM integrator is responsible for the compliance to all the rules that apply to the product into which this certified RF module is integrated.

Additional testing and certification may be necessary when multiple modules are used.

20 cm minimum distance has to be able to be maintained between the antenna and the users for the host this module is integrated into. Under such configuration, the FCC radiation exposure limits set forth for an population/uncontrolled environment can be satisfied.

Any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment.

USERS MANUAL OF THE END PRODUCT:

In the users manual of the end product, the end user has to be informed to keep at least 20 cm separation with the antenna while this end product is installed and operated. The end user has to be informed that the FCC radio-frequency exposure guidelines for an uncontrolled environment can be satisfied. The end user has to also be informed that any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment. If the size of the end product is smaller than 8x10cm, then additional FCC part 15.19 statement is required to be

available in the user manual: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

LABEL OF THE END PRODUCT:

The final end product must be labeled in a visible area with the following " Contains TX FCC ID: 2AFXU-MD903A1 ". If the size of the end product is larger than 8x10cm, then the following FCC part 15.19 statement has to also be available on the label: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.